

Measuring the thermal conductivity of aerogel thin films with time domain thermoreflectance

Patrick E. Hopkins,^{1,2} Bryan Kaehr,^{1,3} Ed, Piekos,¹ Darren Dunphy³
and C. Jeffrey Brinker^{1,3}

1. Microscale Science and Technology Department (01513)

Sandia National Laboratories

Albuquerque, NM, USA

pehopki@sandia.gov

2. Department of Mechanical and Aerospace Engineering

University of Virginia

Charlottesville, VA, USA

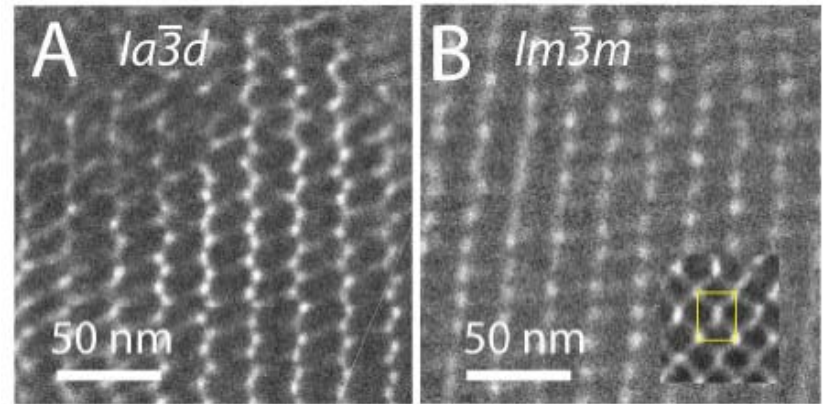
3. Advanced Materials Laboratory

University of New Mexico

Albuquerque, NM, USA

Thermal conductivity of porous nanofilms

- Low thermal conductivities
- Ideal for many applications (insulations, chemical sensors)
- Measurement challenges
 - Brittle
 - Fragile
 - Non conformal (i.e., not specular)
- Porous silica (e.g., aerogels)
 - Transparent
 - Electrically insulative
 - Can “collapse” with contact/pressure



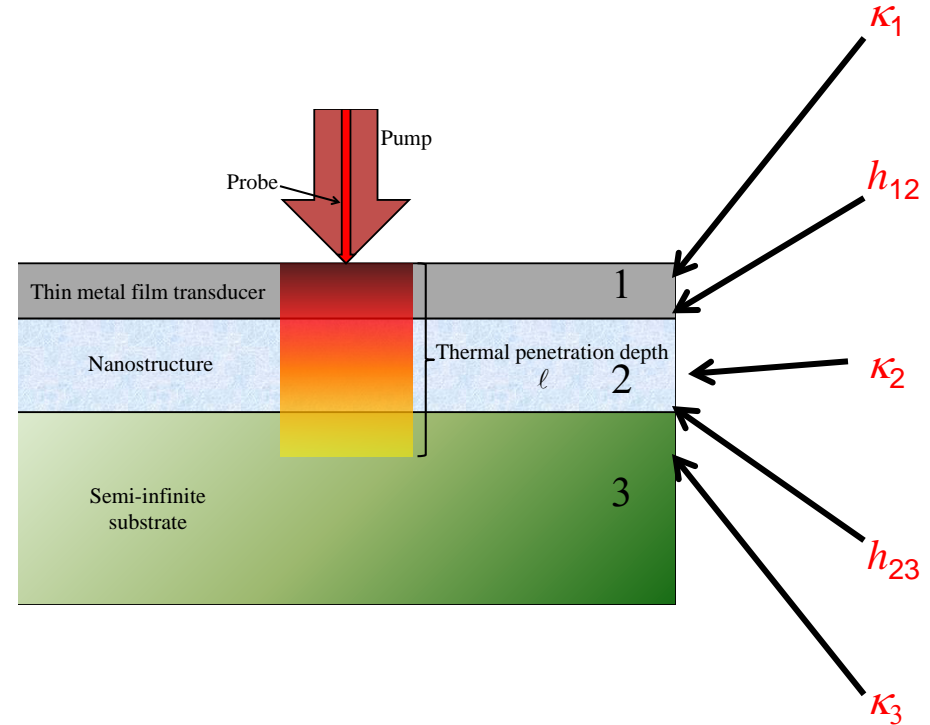
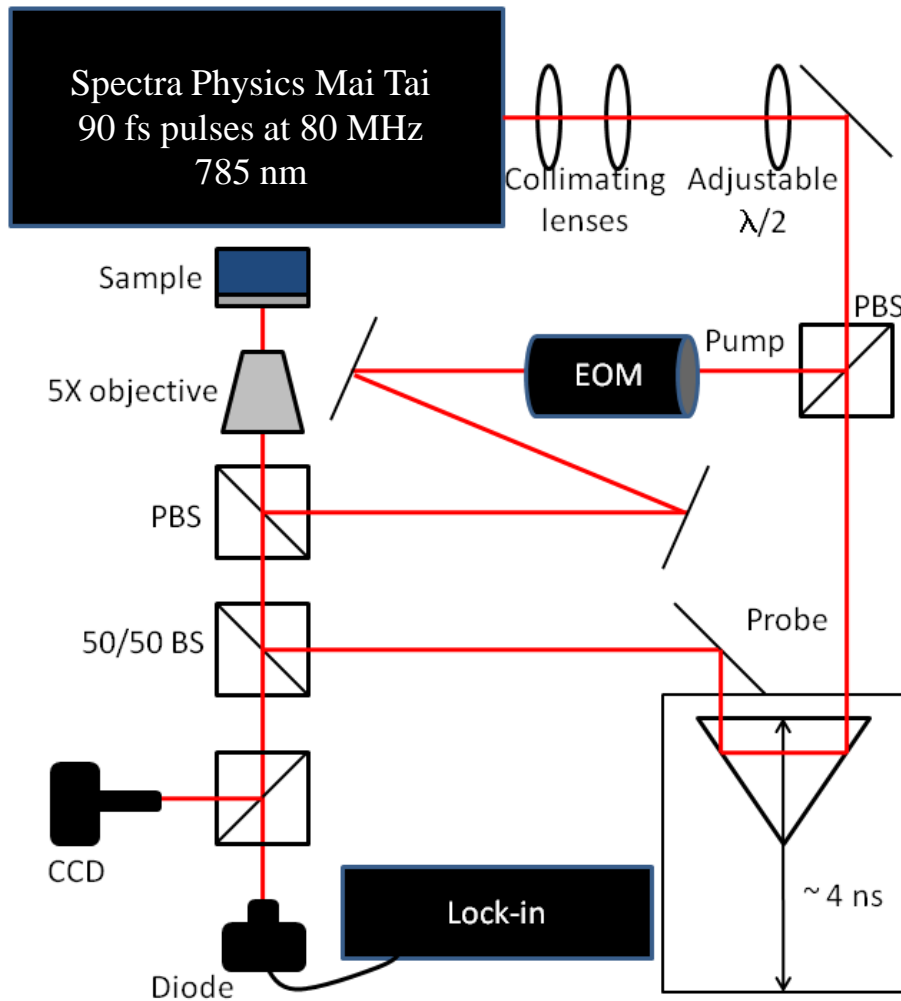
Dunphy *et al.* to appear in
Chemistry of Materials



Outline

- **Time domain thermorefectance – measuring thermal properties of porous samples**
- **Sensitivities and measurements**
- **Thermal conductivity of aerogel thin films**
- **“Porous” minimum limit to thermal conductivity**

Time domain thermorefectance (TDTR)



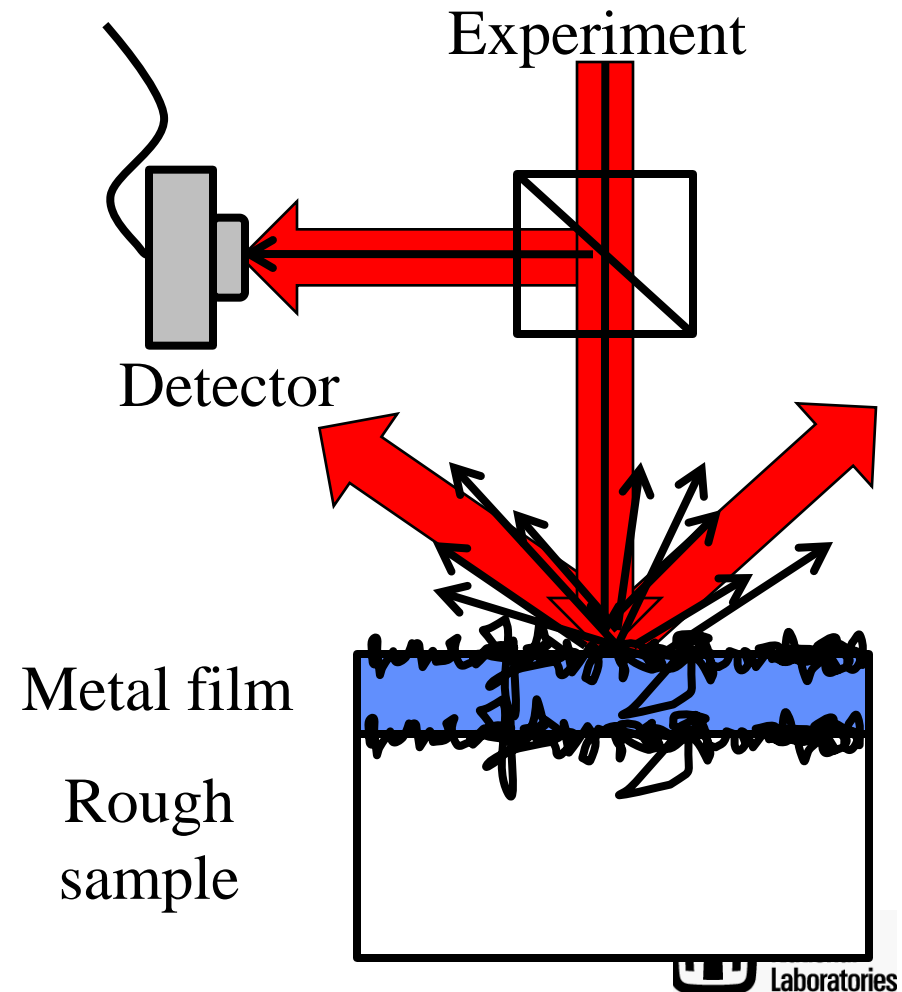
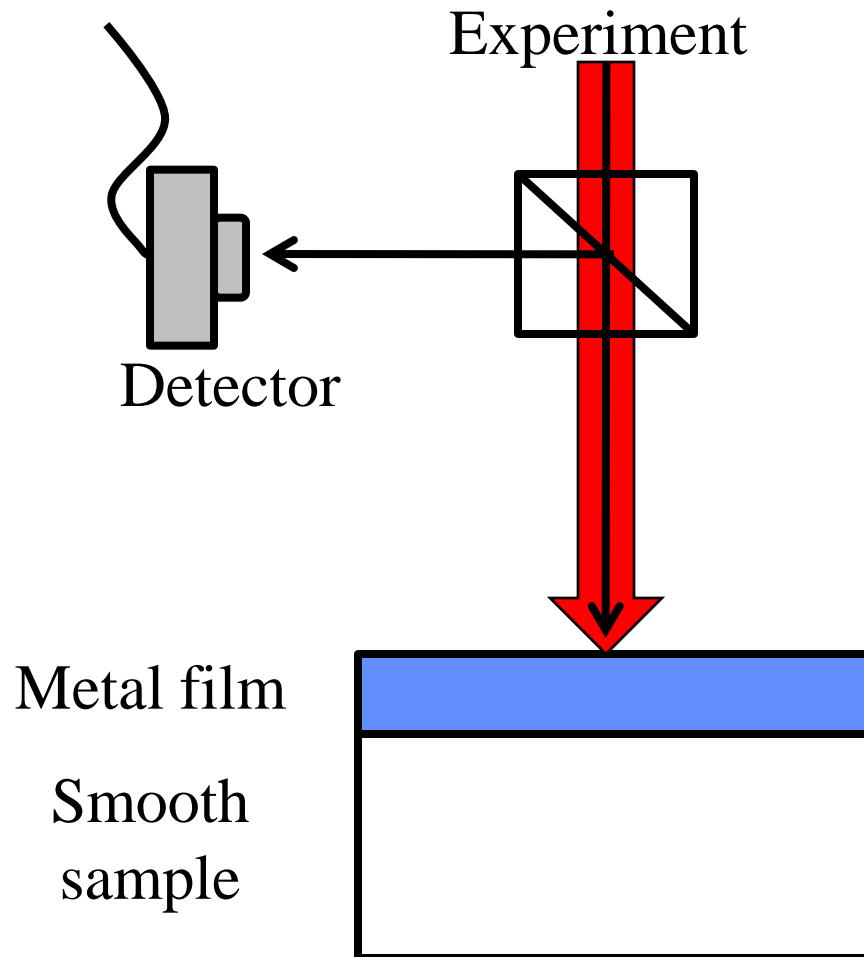
- Can measure thermal conductivity of thin films and substrates (k) separately from thermal boundary conductance (h)
- Nanometer spatial resolution (~ 10 's of nm)
- Femtosecond to nanosecond temporal resolution
- Noncontact

Hopkins, *et al. J. Heat Trans.* **132**, 081302 (2010)

TDTR for nonconformal/non-solid surfaces

TDTR requires a specular, partially reflecting surface

Typical geometry



TDTR for nonconformal/non-solid surfaces

TDTR requires a specular, partially reflecting surface

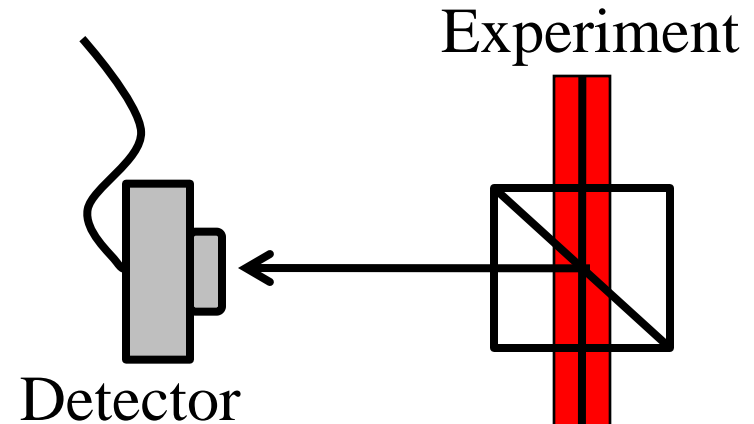
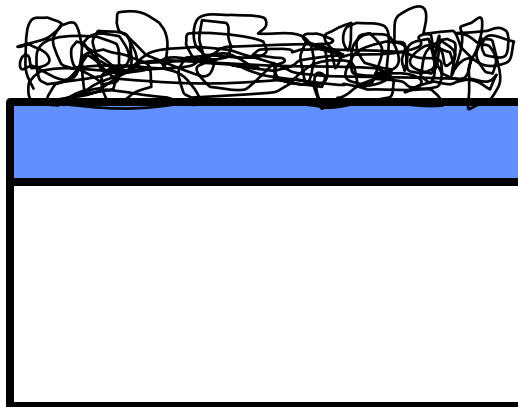
Geometry for rough nanosystem

Coat/fabricate/deposit
nanosystem on metallized
glass slide

Rough/porous film

Metal film

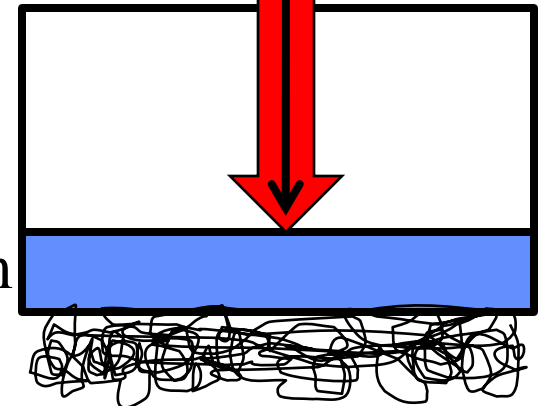
Transparent,
smooth
substrate



Detector

Cover glass

80 nm Al film



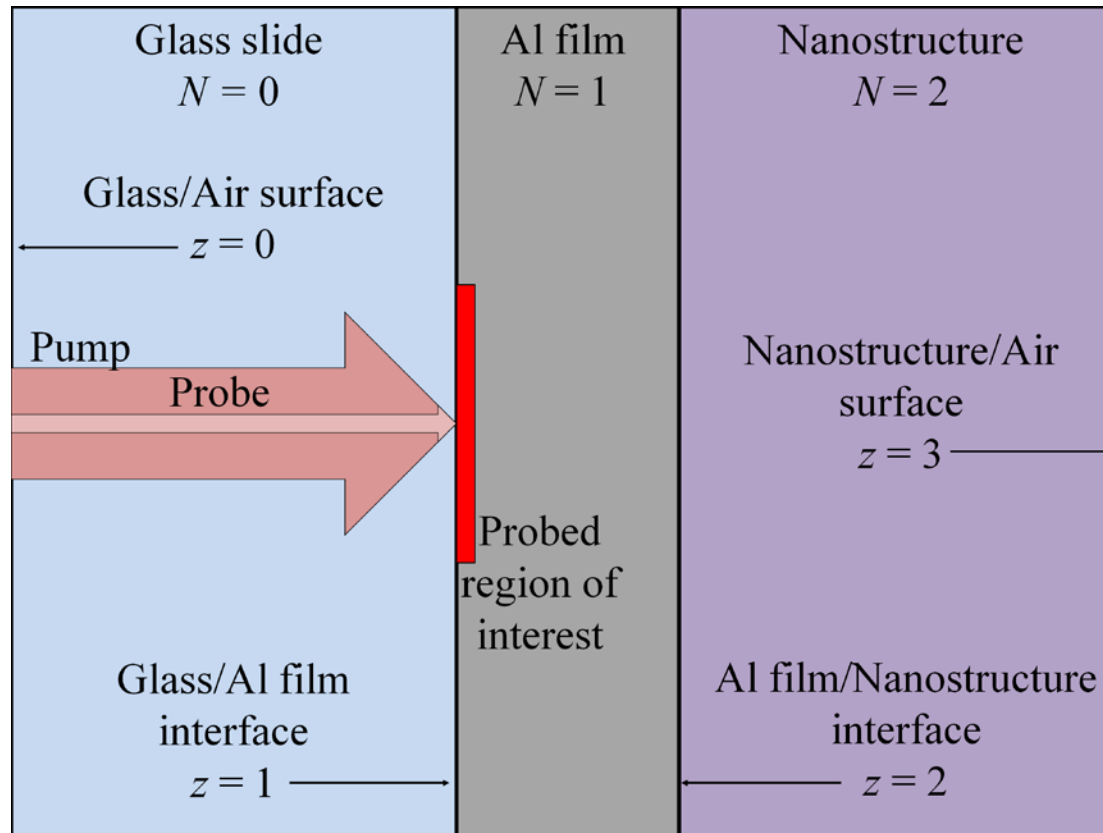
~500 nm aerogel film

TDTR for nonconformal/non-solid surfaces

For liquids: Ge *et al.*, *Phys. Rev. Lett.* **96**, 186101 (2006)

For liquids: Schmidt *et al.*, *Rev. Sci. Instrum.* **79**, 064902 (2008)

For porous composites: Hopkins, *et al.*, *J. Heat Trans.* **133**, 061601 (2011)

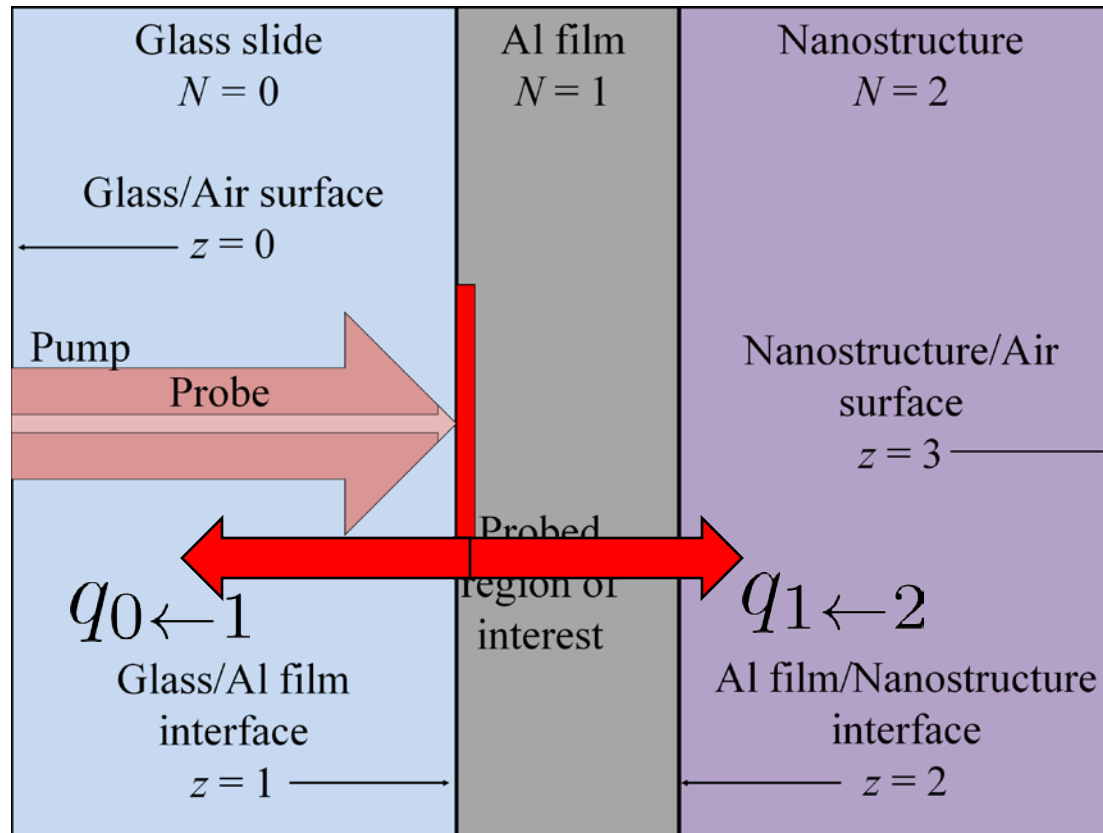


TDTR for nonconformal/non-solid surfaces

For liquids: Ge *et al.*, *Phys. Rev. Lett.* **96**, 186101 (2006)

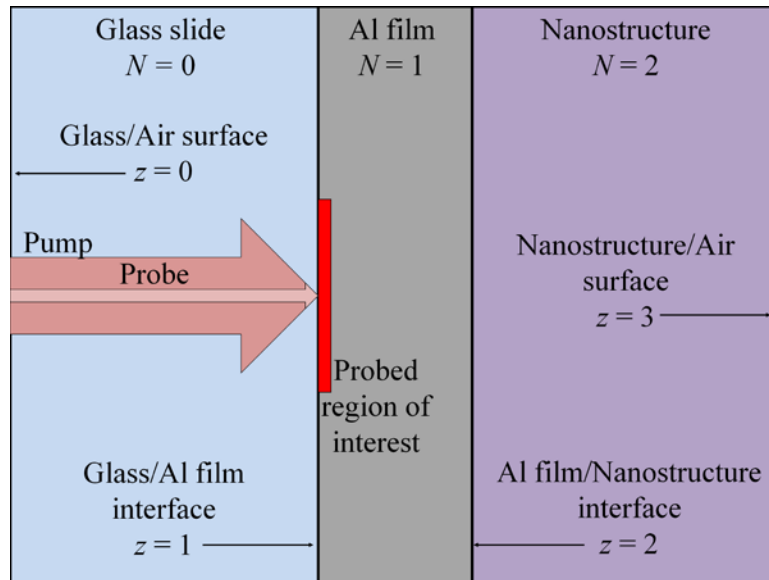
For liquids: Schmidt *et al.*, *Rev. Sci. Instrum.* **79**, 064902 (2008)

For porous composites: Hopkins, *et al.*, *J. Heat Trans.* **133**, 061601 (2011)



Bi-directional heat transfer

TDTR sensitivities



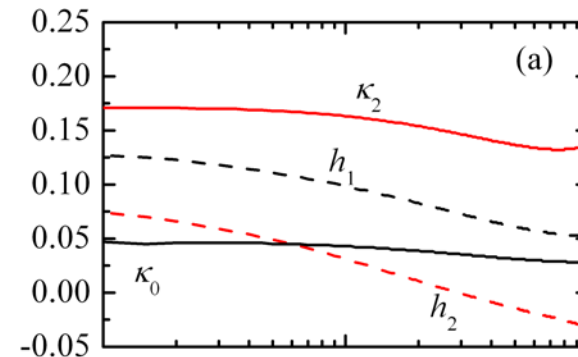
$$S_p = -\frac{\ln[X/Y]}{\ln[p]}$$

S_p - Sensitivity

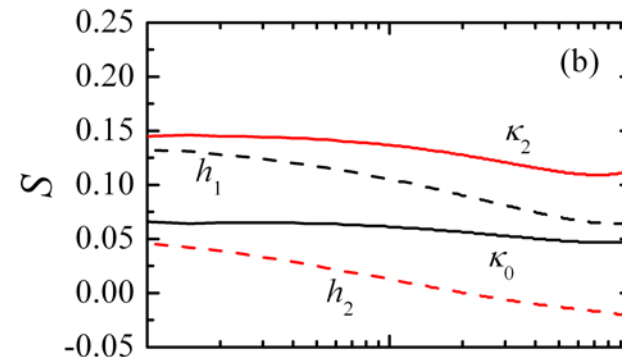
X - Real component

Y - Imaginary component

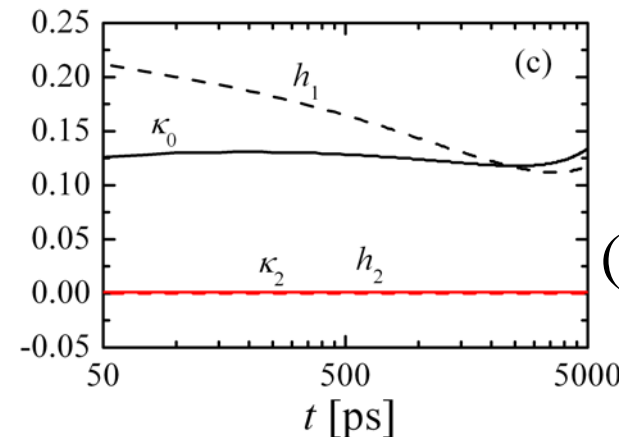
p - property of interest



$N=2$
same as
 $N=0$

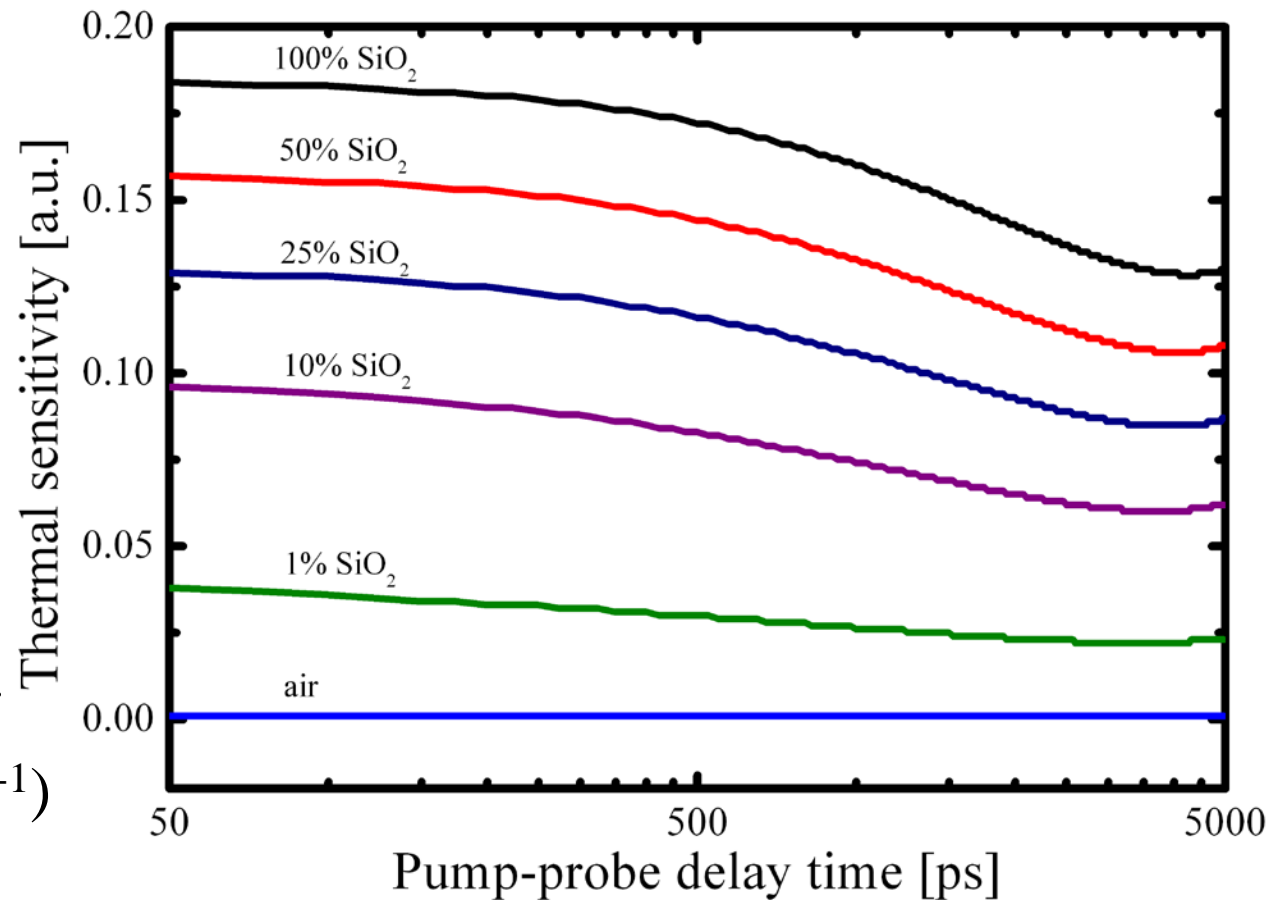
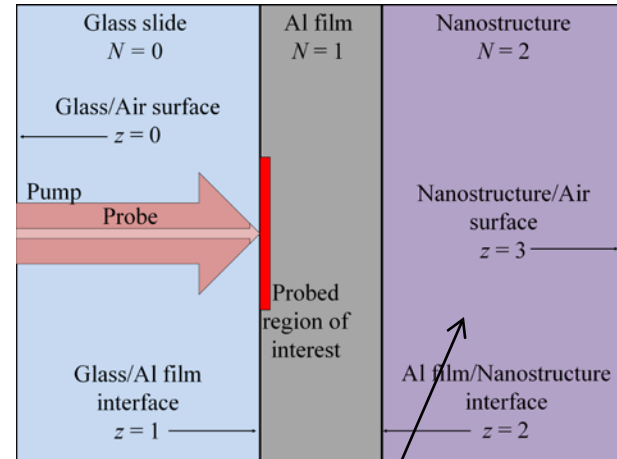


$\kappa_2 = \kappa_0/2$



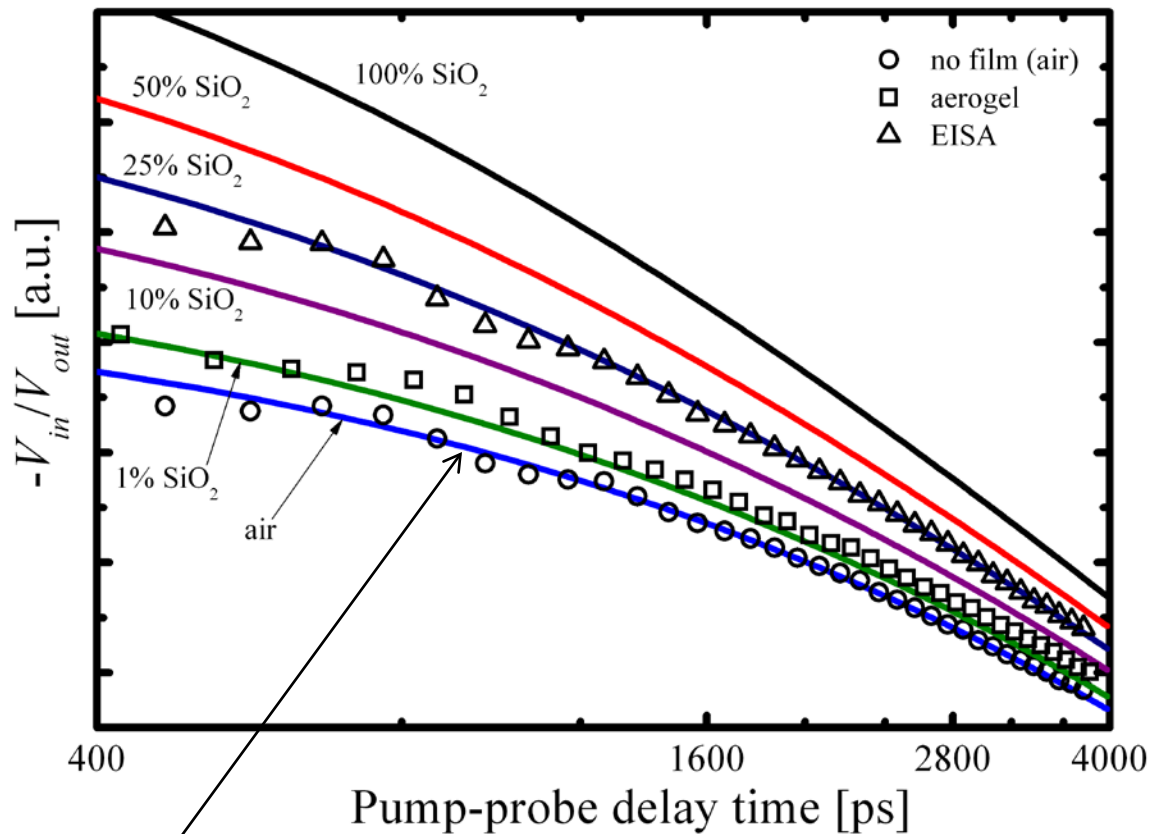
$N=2$
is air
(insulated)

TDTR sensitivity to κ_2

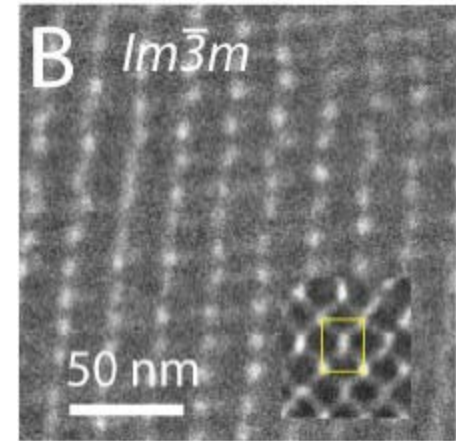


Take κ_2 as some % of bulk κ_{SiO_2} ($1.2 \text{ W m}^{-1} \text{ K}^{-1}$)

TDTR measurements of nanoporous silica films



glass - $\kappa_0 = 1.09 \text{ W m}^{-1} \text{ K}^{-1}$
 Al/glass - $h_1 = 40 \text{ MW m}^{-2} \text{ K}^{-1}$



EISA: Dunphy *et al.* to appear
 in *Chemistry of Materials*

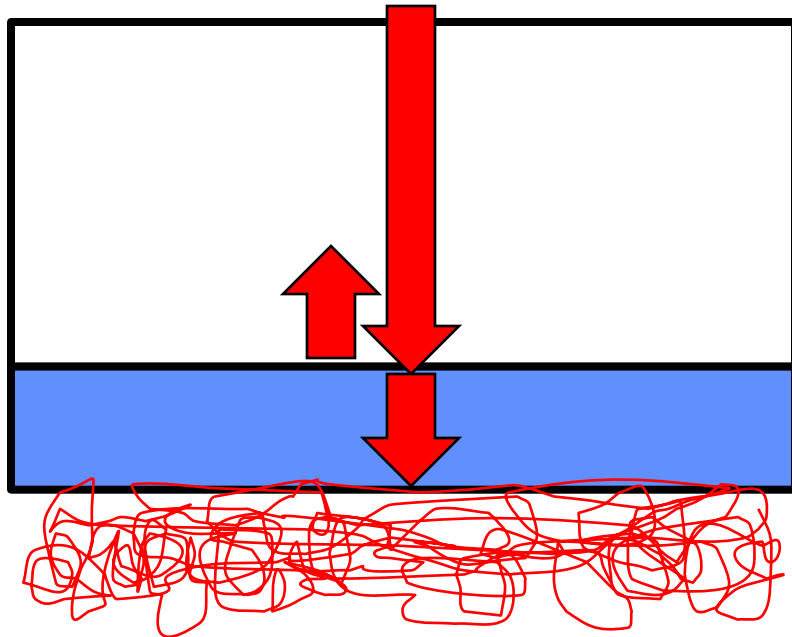
Effusivity measurements of
 nanoporous films

$$E_2 = \sqrt{C_2 \kappa_2}$$

Heat capacity of the sample during TDTR

$$E_2 = \sqrt{C_2 \kappa_2}$$

If no energy is transferred to air in pores,
assume $C_2 = C_2$ of bulk solid



- Measurement only ~4-5 ns in duration
- Not enough time for energy transfer to air
- All energy absorbed in Al film then transferred to solid in nanoporous film

$$h_{solid \rightarrow solid} \gg h_{solid \rightarrow air}$$



Validate bulk heat capacity assumption mathematically

C_2 of porous $\text{SiO}_2 = C_2$ of bulk SiO_2
in TDTR measurements

“Two fluid” model for conduction in porous media (Kaviany, 1991)

Heat conduction in solid part

$$(1 - \phi)C_s \frac{\partial T_s}{\partial t} = (1 - \phi)\kappa_s \nabla^2 T_s - h_{s \rightarrow g}(T_s - T_g) + (1 - \phi)q_{abs,s}$$

Heat conduction in gas part

$$(\phi)C_g \frac{\partial T_g}{\partial t} = (\phi)\kappa_g \nabla^2 T_g + h_{s \rightarrow g}(T_s - T_g) + (\phi)q_{abs,g}$$

Validate bulk heat capacity assumption mathematically

C_2 of porous $\text{SiO}_2 = C_2$ of bulk SiO_2
in TDTR measurements

“Two fluid” model for conduction in porous media (Kaviany, 1991)

Heat conduction in solid part

$$(1 - \phi)C_s \frac{\partial T_s}{\partial t} = (1 - \phi)\kappa_s \nabla^2 T_s - \cancel{h_{s \rightarrow g}(T_s - T_g)} + (1 - \phi)q_{abs,s}$$

Heat conduction in gas part

$$(\phi)C_g \frac{\partial T_g}{\partial t} = (\phi)\kappa_g \nabla^2 T_g + \cancel{h_{s \rightarrow g}(T_s - T_g)} + (\phi)q_{abs,g}$$

•No heat transfer from solid to gas

Validate bulk heat capacity assumption mathematically

C_2 of porous $\text{SiO}_2 = C_2$ of bulk SiO_2
in TDTR measurements

“Two fluid” model for conduction in porous media (Kaviany, 1991)

Heat conduction in solid part

$$(1 - \phi)C_s \frac{\partial T_s}{\partial t} = (1 - \phi)\kappa_s \nabla^2 T_s - \cancel{h_{s \rightarrow g}(T_s - T_g)} + (1 - \phi)q_{abs,s}$$

Heat conduction in gas part

$$(\phi)C_g \frac{\partial T_g}{\partial t} = (\phi)\kappa_g \nabla^2 T_g + \cancel{h_{s \rightarrow g}(T_s - T_g)} + \cancel{(\phi)q_{abs,g}}$$

- No heat transfer from solid to gas
- No energy absorbed in gas from pulse

Validate bulk heat capacity assumption mathematically

C_2 of porous $\text{SiO}_2 = C_2$ of bulk SiO_2
in TDTR measurements

“Two fluid” model for conduction in porous media (Kaviany, 1991)

Heat conduction in solid part

$$(1 - \phi)C_s \frac{\partial T_s}{\partial t} = (1 - \phi)\kappa_s \nabla^2 T_s - \cancel{h_{s \rightarrow g}(T_s - T_g)} + (1 - \phi)q_{abs,s}$$

Heat conduction in gas part

$$\cancel{(\phi)C_g \frac{\partial T_g}{\partial t}} = \cancel{(\phi)\kappa_g \nabla^2 T_g} + \cancel{h_{s \rightarrow g}(T_s - T_g)} + \cancel{(\phi)q_{abs,g}}$$

- No heat transfer from solid to gas
- No energy absorbed in gas from pulse
- Therefore, no heat transfer in gas

Validate bulk heat capacity assumption mathematically

C_2 of porous $\text{SiO}_2 = C_2$ of bulk SiO_2
in TDTR measurements

“Two fluid” model for conduction in porous media (Kaviany, 1991)

Heat conduction in solid part

$$(1 - \phi)C \frac{\partial T}{\partial t} = (1 - \phi)\kappa_s \nabla^2 T + (1 - \phi)q_{abs}$$



$$C_s \frac{\partial T_s}{\partial t} = \kappa_s \nabla^2 T_s + q_{abs,s}$$

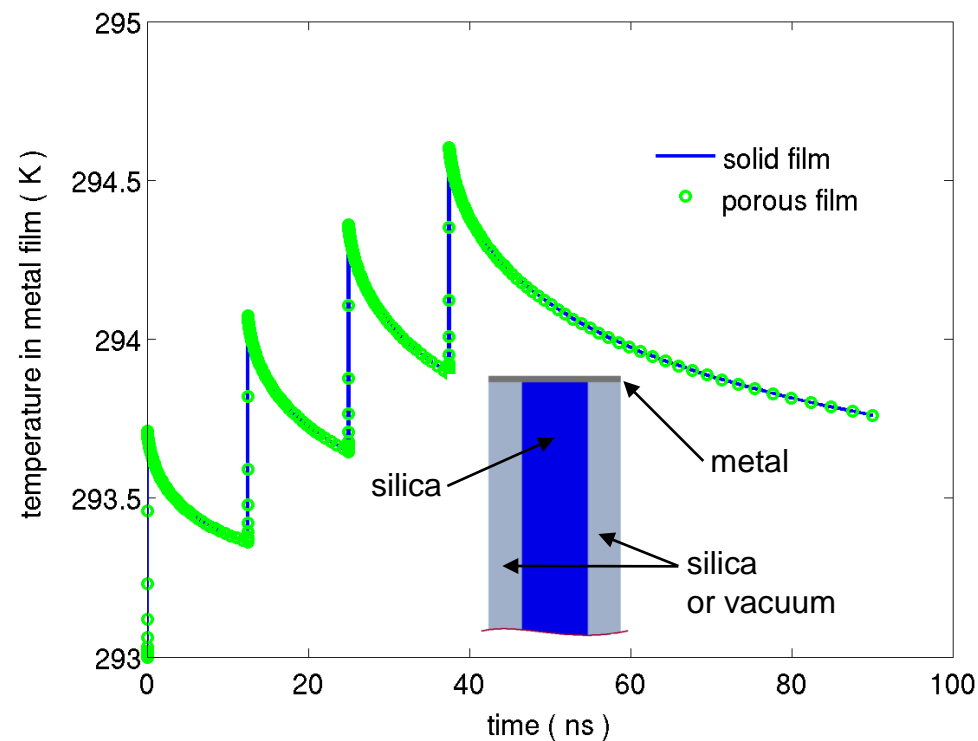
If no energy is transferred to or absorbed by air in nanoporous samples, effective medium does **not** have to be assumed for C_s
to determine κ_s

Validate bulk heat capacity assumption numerically

C_2 of porous $\text{SiO}_2 = C_2$ of bulk SiO_2
in TDTR measurements

If we assume bulk properties in a reduced volume system with insulating pores, does the surface temperature change?

- **FEM simulations of experiment performed**
 - one with solid silica film
 - one with half of silica removed
- **In half-silica cases, all fluxes from metal were superposed on remaining silica**
- **Temperature measured in metal film**
- **No discernable difference observed in results**



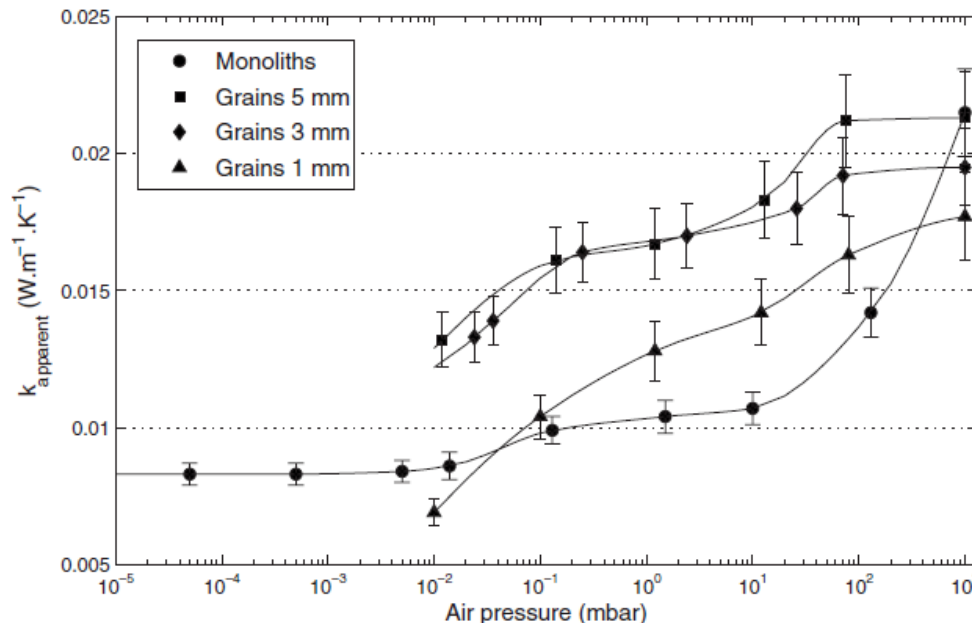
Validate bulk heat capacity assumption experimentally

Measure effusivity of aerogel films in ambient and under vacuum

Aerogel films: Prakash, Brinker, Hurd, *J. Non-Crystalline Solids* **190**, 264 (1995)

$$E_{\text{aerogel}, P < 10^{-3} \text{ mbar}} = \sqrt{C\kappa} = 223 \pm 95 \text{ W m}^{-2} \text{ K}^{-1} \sqrt{s}$$

$$E_{\text{aerogel}, P = \text{ambient}} = \sqrt{C\kappa} = 233 \pm 121 \text{ W m}^{-2} \text{ K}^{-1} \sqrt{s}$$



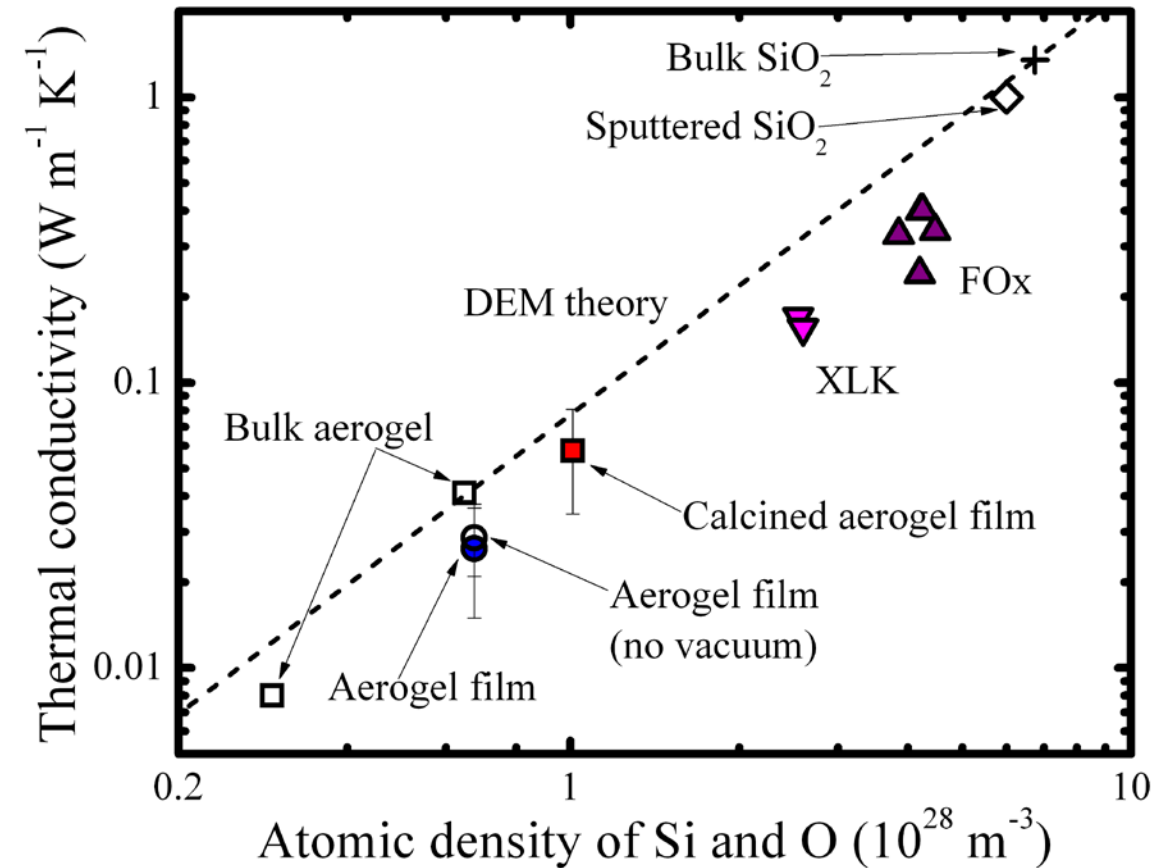
Time scale of
measurement too short to
allow any thermal
diffusion into air in pores
(~4 – 5 ns)



Outline

- Time domain thermoreflectance – measuring thermal properties of porous samples
- Sensitivities and measurements
- Thermal conductivity of aerogel thin films
- “Porous” minimum limit to thermal conductivity

Thermal conductivity of aerogel thin films



Differential Effective Medium (DEM) theory

$$\kappa_{\text{porous}} = \kappa_{\text{solid}} \left(\frac{n_{\text{porous}}}{n_{\text{solid}}} \right)^{\frac{3}{2}}$$

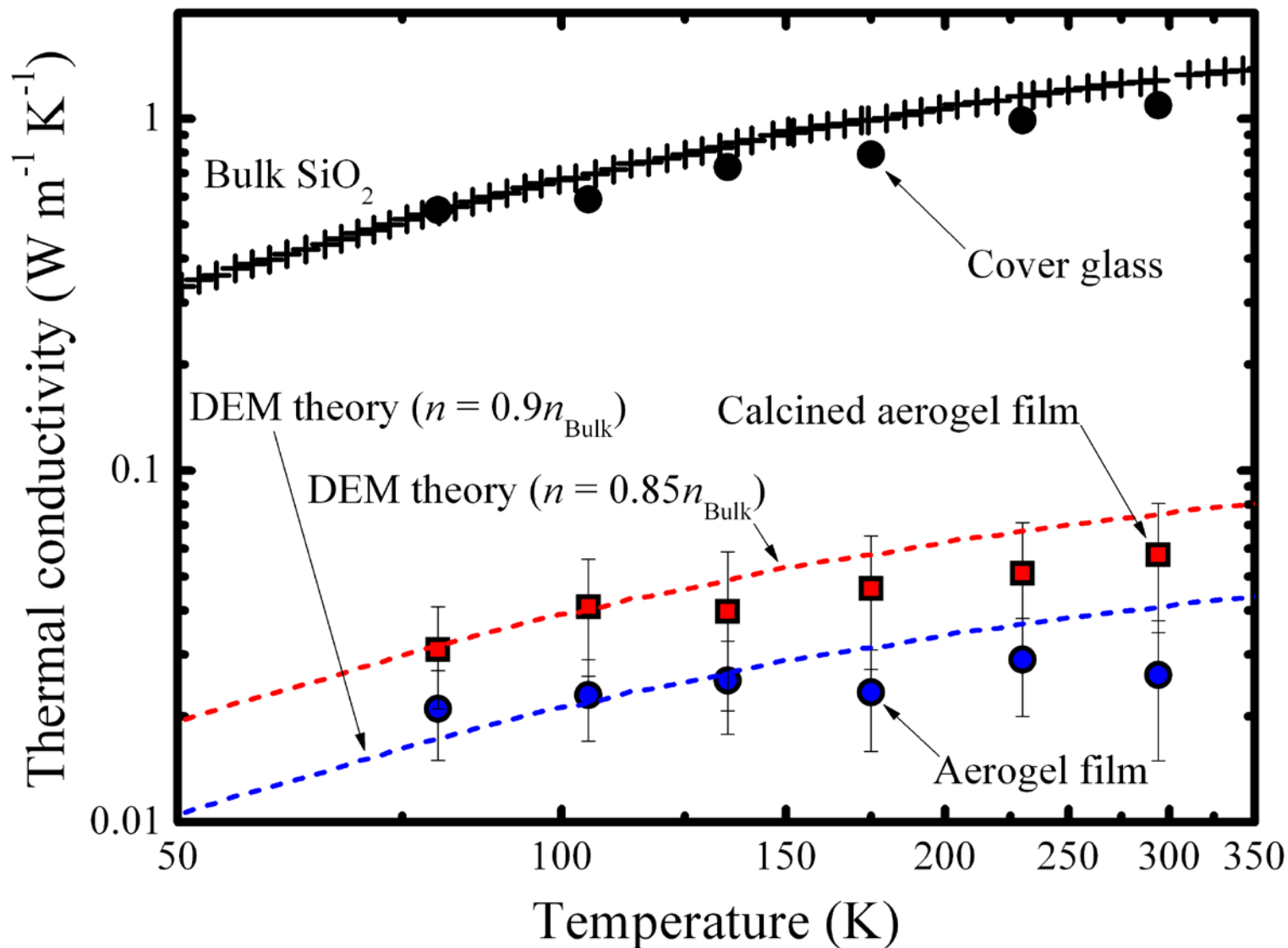
SiO_2 , Fox, and XLK data: Costescu *et al.*, *Phys Rev. B* **65**, 094205 (2002)

Bulk aerogel data: Spagnol *et al.*, *J. Heat Trans.* **131**, 074501 (2009)

& Wei *et al.*, *J. Phys. Chem. C* **113**, 7424 (2009)

DEM: Bruggeman, *Ann. Phys.* **416**, 636 (1935)

Thermal conductivity of aerogel thin films





Outline

- Time domain thermoreflectance – measuring thermal properties of porous samples
- Sensitivities and measurements
- Thermal conductivity of aerogel thin films
- **“Porous” minimum limit to thermal conductivity**



Lower limit to thermal conductivity

Thermal conductivity

$$\kappa = \frac{1}{3} C v \lambda = \frac{1}{3} C v_g v_p \tau$$

Scattering time is half period of oscillation (i.e. atomic spacing limited)

Einstein, *Annalen der Physik* **35**, 679 (1911) and Cahill *et al.*, *Phys. Rev. B* **46**, 6131 (1992).

$$\tau = \frac{\pi}{\omega} \rightarrow \kappa = \frac{1}{3} C v_g v_p \frac{\pi}{\omega}$$

Scattering destroys “phase” of oscillation (“diffusive” scattering)

Hopkins and Beechem, *Nano. Micro. Thermophys. Eng.* **14**, 51 (2010).

$$v_g \neq v_p = \frac{\pi}{n^{1/3} \omega} \rightarrow \kappa = \frac{n^{-1/3}}{3} C v_g \frac{\pi^2}{\omega^2}$$

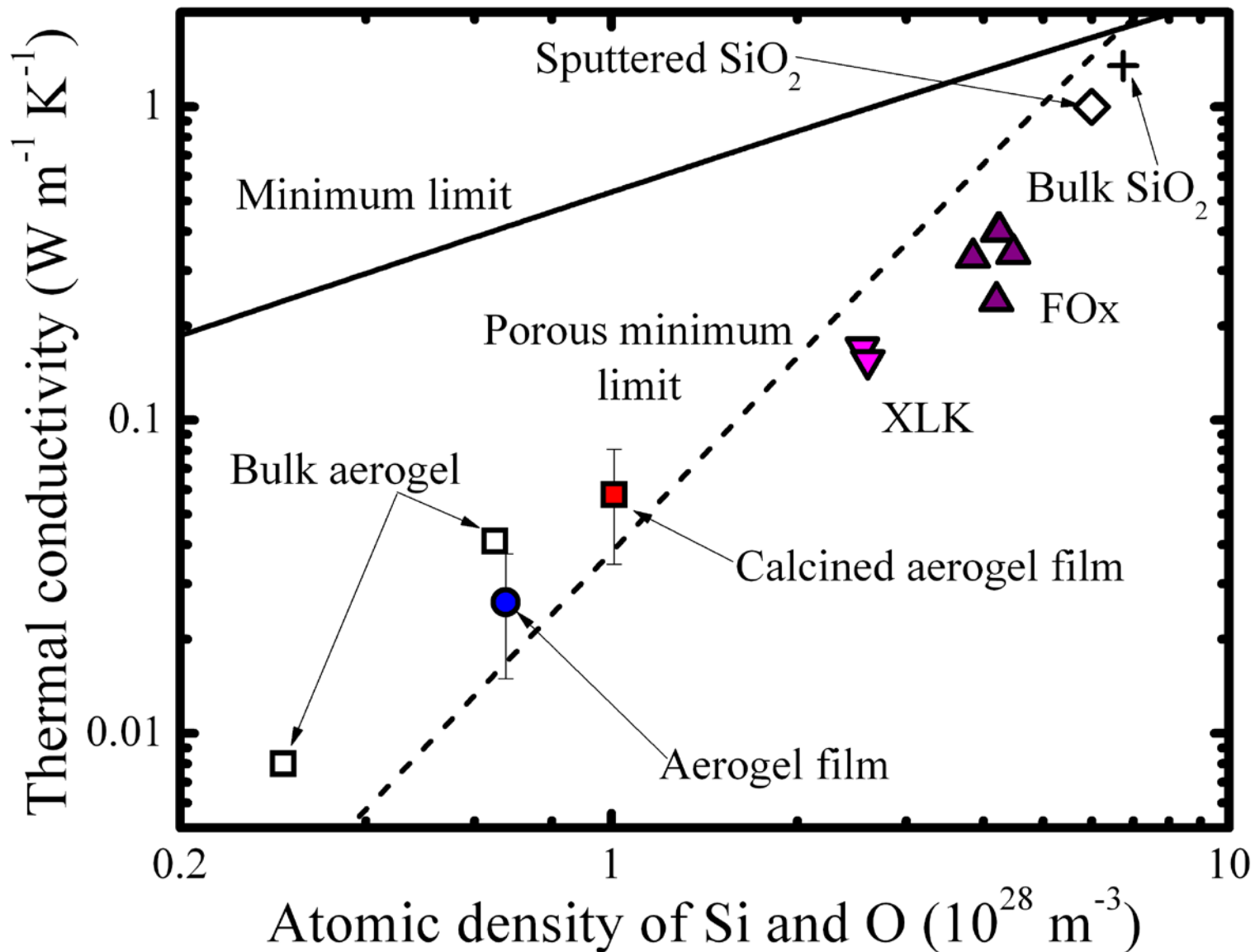
Assume Debye solid

$$\kappa = \left(\frac{\pi^2}{36} \right)^{1/3} n^{2/3} k_B \sum_j \frac{T}{\Theta_j} v_{g,j} \int_0^{\Theta_j/T} \frac{x^2 \exp[x]}{(\exp[x] - 1)^2} dx$$

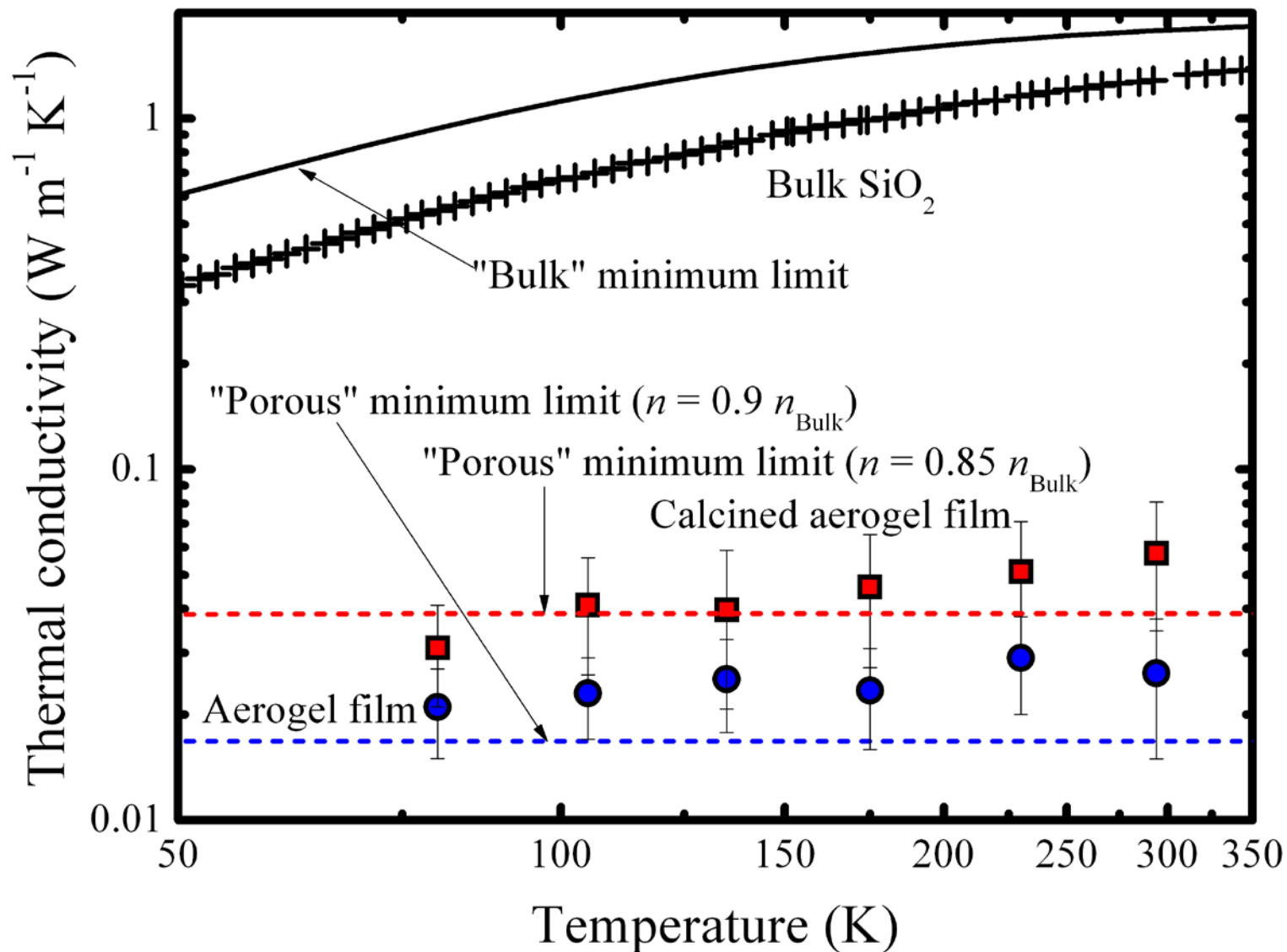
For porous media $v_g \propto n^{1.4}$

Costescu *et al.*, *Phys Rev B* **65**,
094205 (2002).

“Porous” minimum limit



“Porous” minimum limit





Summary

- **TDTR can be used to measure thermal conductivity of porous materials with minimal losses from air in pores**
- **TDTR measurement is dominated by heat flow in the solid matrix due to time scale of measurements**
- **Thermal conductivity of aerogel thin films agrees with bulk aerogels with similar densities**
- **Porous minimum limit gives better estimate of thermal conductivity than traditional minimum**
- Thanks to: Harry S. Truman Fellowship program at Sandia (Hopkins and Kaehr), LDRD program at Sandia (Piekos and Brinker)